

July 2st, 2004, Friday			
<b>Session No 12:</b> Emerging technology and environmental issues			
Chair	Prof. Z N Cheng SMIT Center, Chalmers University of Technology & Shanghai University		
Co-Chair	Dr. Shiwei Ma SMIT Center, Shanghai University		
Venue	Room 2		
Time	No. of Paper	Title	Speaker
15:50-16:10	S12-1	Diamond Film/Alumina Composites Used as the Packaging Material in Integrated Circuits with Ultra-High Speed and High Power	Yiben Xia School of Materials Science and Engineering, Shanghai University (Invited)
16:10-16:30	S12-2	Integrating Nano Carbotubes With Microchannel Cooler	Zhimin Mo SMIT Center and Division of Electronics Production, Chalmers University of Technology, Sweden
16:30-16:50	S12-3	A novel surface passivation process for CdZnTe detector packaging	Sang Wenbin Department of Electronic Information Materials, Shanghai University
16:50-17:10	S12-4	Polymer-assisted Self-assembling Orientation Growth of ZnO Nanorods	Ying He School of Materials Science and Engineering, Shanghai University
17:10-17:30	S12-5	The improvement on the properties of silver-containing conductive adhesives by the addition of Carbon Nanotube	Lin Xuechun shenzhen polytechnic, xilihu, shenzhen, china
17:30-17:50	S12-6	A BS-BIST Test Circuit Design for VAD-SOC	Li Jianfeng the Microelectronic Research and Developing Center, Shanghai University
17:50-18:10	S12-7	Design and Implementation of RS (255,223) Decoder on FPGA	Yan Laijin the Microelectronics Research and Developing Center, Shanghai University
18:30-21:30	Conference Dinner		

